

Microbonds



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TANAKA AND MICROBONDS ANNOUNCE LICENSE AGREEMENT FOR X-WIRE™ TECHNOLOGY

Tanaka to manufacture X-Wire™ Technology at its production facilities

TOKYO, Japan & TORONTO, Canada, (March 24, 2006) - Tanaka Denshi Kogyo K.K., the leading global supplier of standard bare gold bonding wire, and Microbonds Inc., the inventor of insulation for gold bonding wires and related processes, today announced they have reached an agreement where Microbonds proprietary X-Wire™ Technology will be licensed to Tanaka for application to the Tanaka family of gold bonding wire products. Initial production will occur at Tanaka's flagship Saga Japan facility.

“Our long-term relationship with Microbonds will allow us to offer our customers a unique and compelling solution to many interconnect challenges” said Hugh Okamoto, CEO of parent Tanaka Kikinzoku Group.

“The benefits of insulating gold bonding wires to solve interconnect challenges associated with smaller packages and design limitations is well understood by our industry”, added Yasuo Fukui, President of Tanaka Denshi Kogyo K.K. “However until Microbonds unlocked certain advances in chemistry and process, these benefits could not be achieved”.

Jan Vardaman, President of TechSearch International Inc., the industry's leading semiconductor assembly and materials consultancy commented, “The relentless trend towards smaller packages with more functionality requires advances in interconnect technology. The industry has been waiting for many years for a proven insulated wire technology that can be used with existing equipment and packaging processes. In addition, the ability to reduce gold costs by using smaller diameter insulated bonding wires relieves some of the buildup of gold cost pressures”

“Microbonds is honored to have reached this milestone with the Tanaka Group. We look forward to meeting global market demand with a partner known for its long term commitment to quality, technical leadership and market responsibility”, said John Scott, CEO of Microbonds Inc.

“Together we are targeting for initial Tanaka X-Wire™ volumes to be available from Tanaka sometime in Q4/06. Until then we will continue to satisfy customer requirements for our X-Wire 2.0™ product from our current production facilities” added Craig Geier, CFO and EVP Corporate Development.

About X-Wire Technology

Microbonds' X-Wire™ Technology is an interconnect solution which consists of a proprietary insulation applied to bare gold bonding wires, advances to the assembly

processes, equipment and procedures required to utilize insulated bond wire with the existing wire bonding infrastructure.

X-Wire™ Technology enables interconnect bonding wires to touch and cross without causing an electrical short. With X-Wire™, customers can solve yield losses due to wire sweep, increase I/O counts, achieve new geometries through new bonding rules, as well as reduce costs through direct to ball bonding and thinner diameter wires.

About Tanaka

Tanaka Kikinzoku Group is a global provider of precious metal materials, such as bonding wires and targets that support the production of semiconductor devices from wafer to assembly processing. Based in Tokyo, Japan, the company has been in business for over 100 years. Its products play a vital role in the industrial fields, such as energy conservation, environmental control, health care, electric and electronics, automobile, telecommunication and semiconductors.

For more information, please visit: www.tanaka-precious.com

About Microbonds

Microbonds, Inc. is a pioneer in the development of unique microchip-interconnect solutions for use in the design and assembly of microelectronic devices. The company's X-Wire Technology enables the development of faster, smaller and cheaper microchips while improving manufacturing reliability by providing an insulating coating on gold bonding wires.

For more information, see www.microbonds.com

About TechSearch International, Inc.

TechSearch International, Inc., founded in 1987, is a technology licensing and consulting company specializing in microelectronics packaging and assembly technologies. Single and multi-client services encompass technology licensing, strategic planning, and market and technology analysis.

For more information, see www.techsearchinc.com

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For more information:

Tanaka
Andrew Farry
Tanaka Kikinzoku Int'l
Tel: 1-317-598-0796
a-farry@ml.tanaka.co.jp

Microbonds
John M. Scott
President & CEO
Tel: 1-905-305-0980
Ext. 222
jscott@microbonds.com